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REPLY UNDER
37 C.F.R. § 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 2814

PATENT
0763-0173P

Please enter LP (4/5/04)
IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Dong K. SOHN et al. Conf.: 9674
Appl. No.: 10/620,608 Group: 2814
Filed: July 17, 2003 Examiner: Long Pham
For: METHOD OF FORMING FILM FOR REDUCED
OHMIC CONTACT RESISTANCE AND TERNARY
PHASE LAYER AMORPHOUS DIFFUSION BARRIER

REPLY AFTER FINAL UNDER 37 C.F.R. § 1.116

MS AF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

October 28, 2004

Sir:

In reply to the outstanding Office Action dated August 2, 2004, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes: amendments to the specification, claims and remarks.